



• General Description

It combines trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- AEC-Q101 Qualified
- Low $R_{DS(ON)}$ to minimize conductive loss
- High GOX reliability
- Low Thermal resistance

• Application

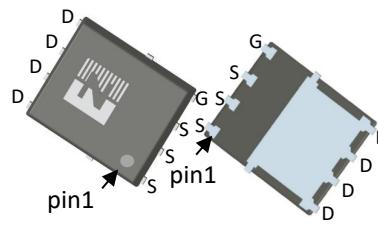
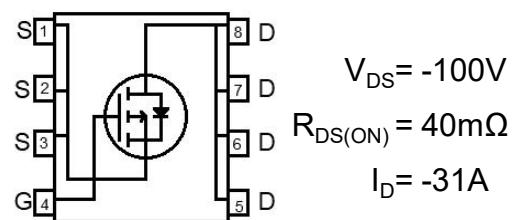
- BLDC Motor driver
- DC-DC
- Load switch

• Ordering Information:

Part NO.	ZMA350P10N
Marking	ZM350P10
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

• Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		-100	V
Gate-Source Voltage ^①	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_c=25^\circ\text{C}$	-31	A
	I_D	$T_c=75^\circ\text{C}$	-26	A
	I_D	$T_c=100^\circ\text{C}$	-22	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu\text{s}$; $T_{mb} = 25^\circ\text{C}$	-124	A
Total Power Dissipation	P_D	$T_c=25^\circ\text{C}$	115	W
Total Power Dissipation	P_D	$T_A=25^\circ\text{C}$	3.3	W
Operating Junction Temperature	T_J		-55 to +175	$^\circ\text{C}$
Storage Temperature	T_{STG}		-55 to +175	$^\circ\text{C}$
Single Pulse Avalanche Energy	E_{AS}	$L=0.1\text{mH}$, $V_{GS}=-10\text{V}$, $R_g=25\Omega$,	110	mJ
		$L=0.5\text{mH}$, $V_{GS}=-10\text{V}$, $R_g=25\Omega$,	231	mJ
ESD Level (HBM)			CLASS 2	





•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}		-	1.3	°C/W
Thermal resistance, junction-ambient ^②	R _{thJA}		-	45	°C/W
Soldering temperature	T _{sold}		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = -250uA	-100			V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = -250uA	-1.3	-1.8	-2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{GS} =0V, V _{DS} = -100V			1.0	uA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D = -15A		40	56	mΩ
		V _{GS} =-4.5V, I _D = -8A		52	70	mΩ
Forward Transconductance	g _{FS}	V _{DS} = -5V, I _{SD} = -10A		20		s
Diode Forward Voltage	V _{FSD}	V _{GS} = 0V, I _{SD} = -15A			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz, V _{DS} =-25V	-	4500	-	pF
Output capacitance	C _{oss}		-	398	-	
Reverse transfer capacitance	C _{rss}		-	157	-	
Gate Resistance	R _g	f = 1MHz	-	4		Ω
Total gate charge	Q _g	V _{DD} = -15V, I _D = -10A, V _{GS} = -10V	-	124	-	nC
	Q _{g(-4.5v)}		-	61	-	
Gate - Source charge	Q _{gs}	V _{GS} = -10V	-	20	-	nC
Gate - Drain charge	Q _{gd}		-	29	-	
Turn-ON Delay time	t _{D(on)}	V _{GS} =-10V, V _{DS} =-15V, R _G = 3.3Ω, I _D = -10A	-	26	-	ns
Turn-ON Rise time	t _r		-	89	-	ns
Turn-Off Delay time	t _{D(off)}		-	96	-	ns
Turn-Off Fall time	t _f		-	67	-	ns
Reverse Recovery Time	t _{RR}	V _{DD} =-20V, dI _S /dt = 100A/us, I _S =-20A	-	205	-	ns
Reverse Recovery Charge	Q _{RR}		-	467	-	nC



Fig.1 Gate-Charge Characteristics

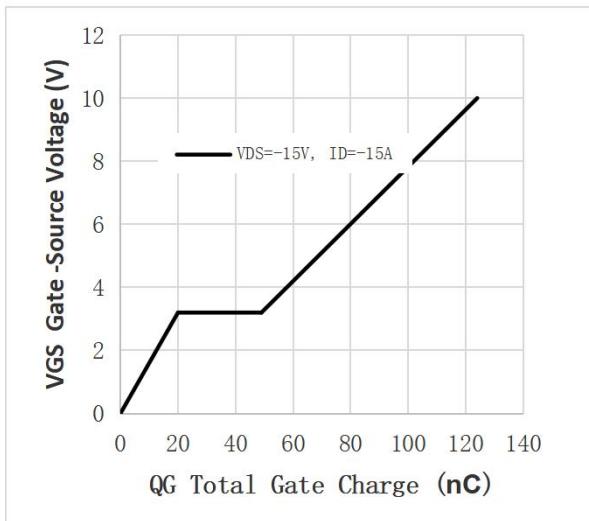


Fig.2 Capacitance Characteristics

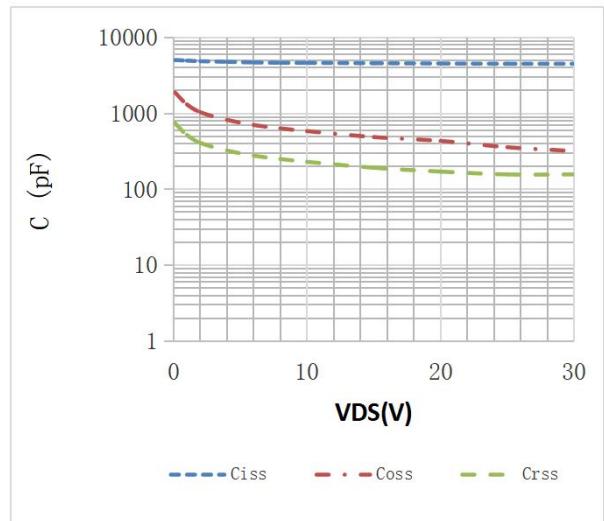


Fig.3 Power Dissipation

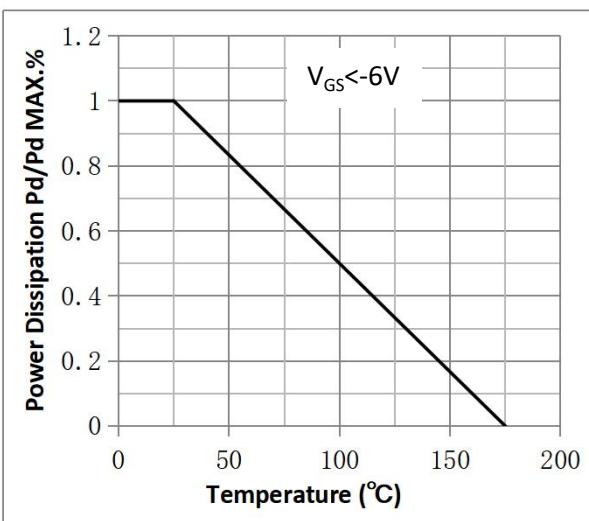


Fig.4 Typical output Characteristics

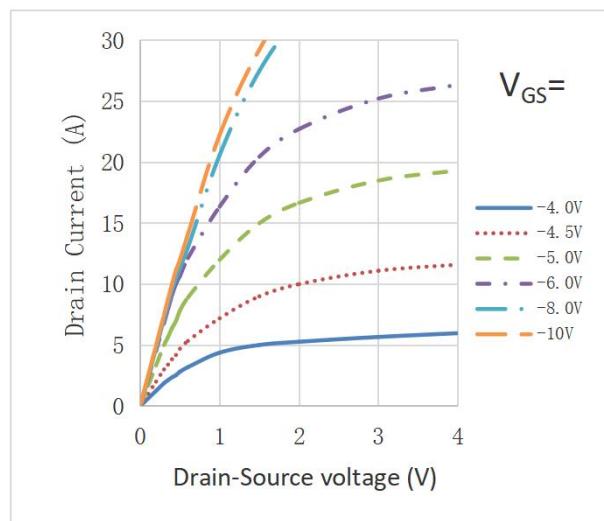


Fig.5 Threshold Voltage V.S Junction Temperature

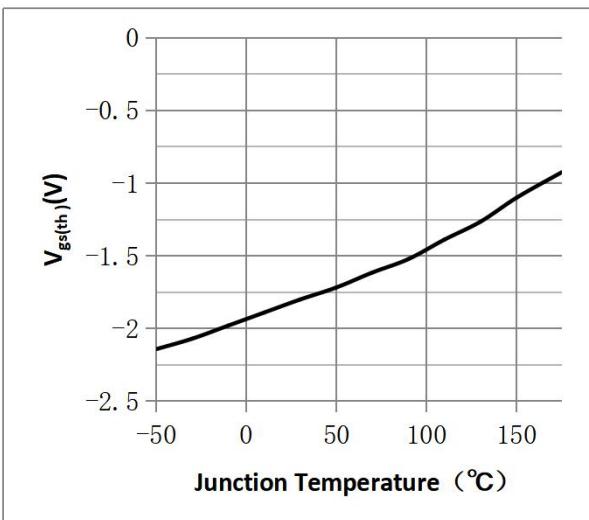


Fig.6 Resistance V.S Drain Current

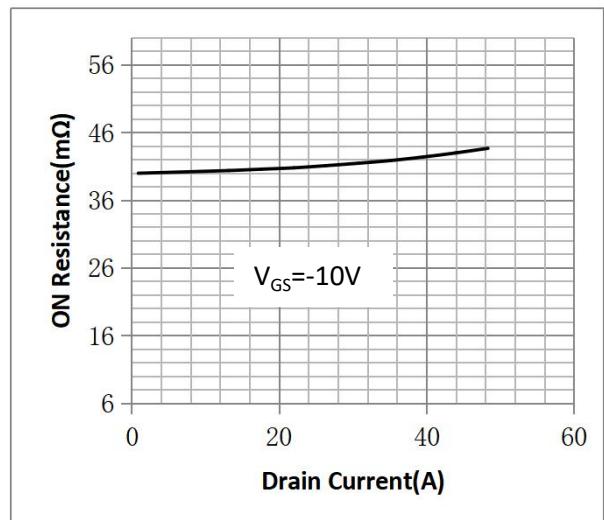


Fig.7 On-Resistance VS Gate Source Voltage

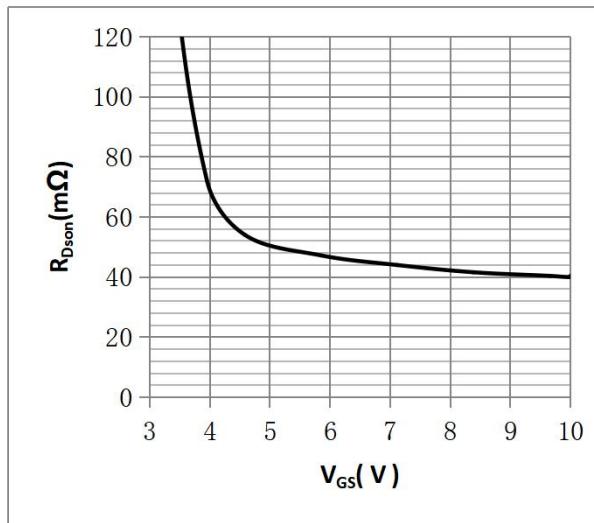


Figure 9. Diode Forward Voltage vs. Current

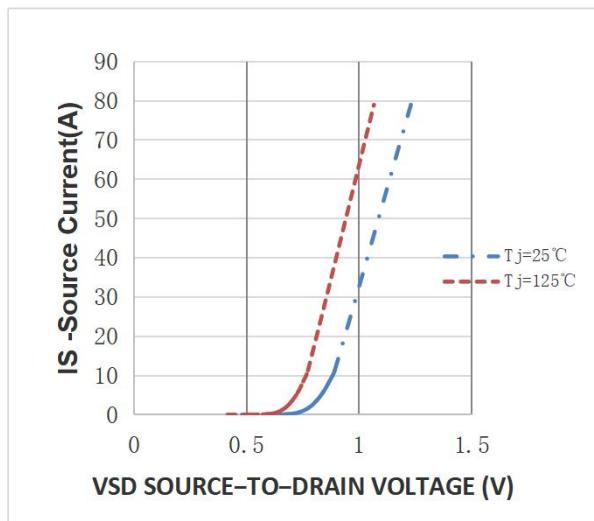


Fig.11 Safe Operating Area

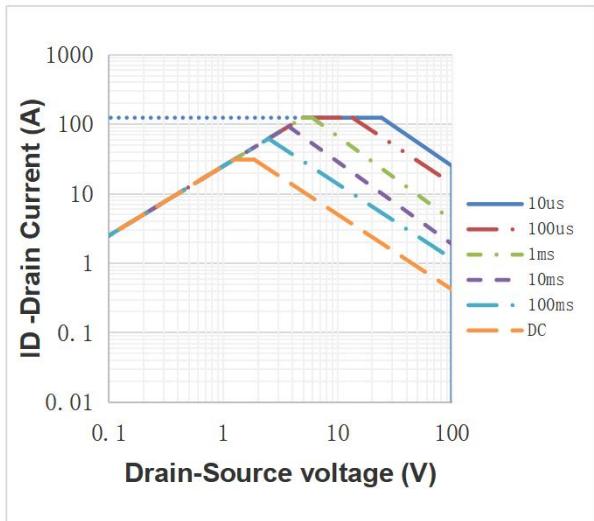


Fig.8 On-Resistance V.S Junction Temperature

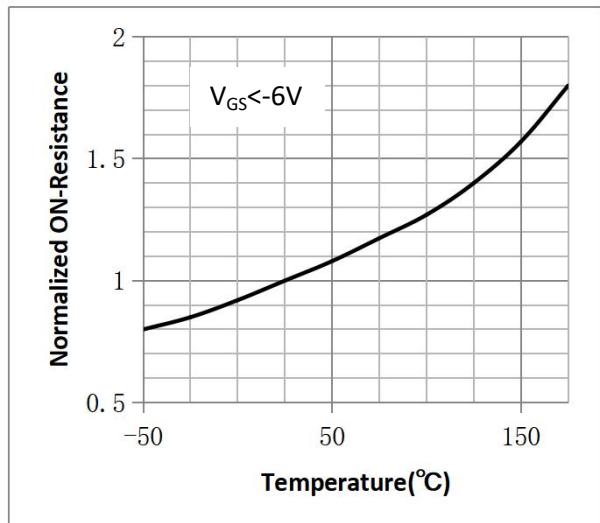
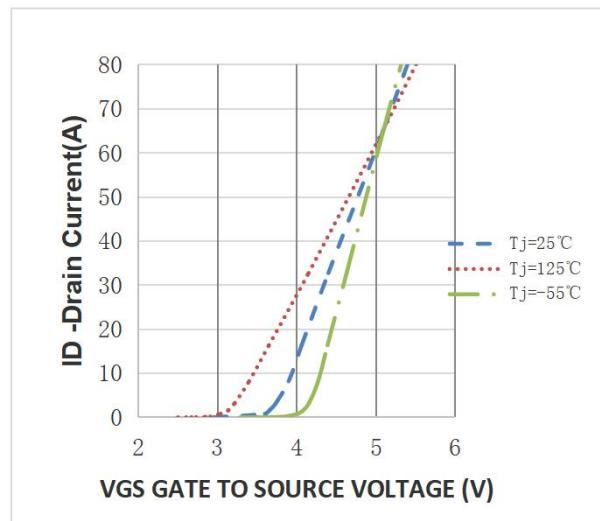
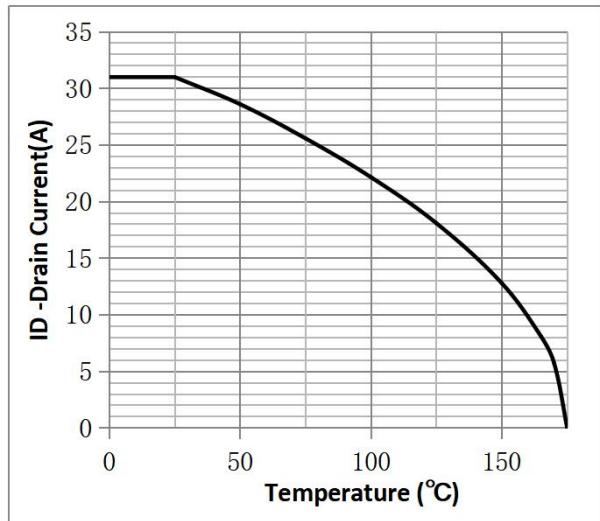
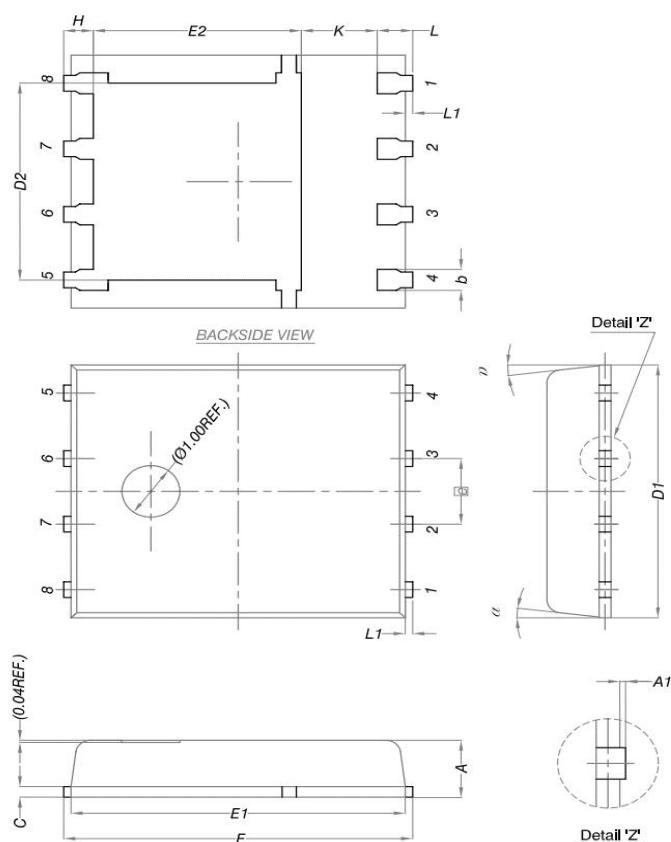


Figure 10. Transfer Characteristics

Fig.12 ID vs. Case Temperature^③



•DFN5*6 Package Outline



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
α	0°	-	12°

**Note:**

- ① Pulse : VGS=+20V/-20V, Duty cycle=50%, Tj=175°C, t=1000 hours; For DC , the following test conditions can be passed: VGS=-20V/+10V, Tj=175°C, t=1000 hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. VGS=-10V.

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Revision History

Version	Date	Change
A	2021.12.3	NEW
B	2022.9.7	1.Add Reach, HF figure